



## DESCRIPTION

The MBR120E~MBR1200E is available in SOD-323HE Package

## ORDERING INFORMATION

Package Type	Part Number
SOD-323HE	MBR120E
	MBR130E
	MBR140E
	MBR150E
	MBR160E
	MBR180E
	MBR1100E
	MBR1150E
	MBR1200E
Note	SPQ: 3,000pcs/Reel
AiT provides all RoHS Compliant Products	

## FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Low power loss, high efficiency
- For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- Guarding for over voltage protection
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Available in SOD-323HE Package

## MECHANICAL DATA

Case: SOD-323HE

molded plastic over sky die

Terminals: Tin Plated, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.011 g

Handling precaution: None

## PIN DESCRIPTION





## MAXIMUM & THERMAL CHARACTERISTICS RATINGS

at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	MBR 120E	MBR 130E	MBR 140E	MBR 150E	MBR 160E	MBR 180E	MBR 1100E	MBR 1150E	MBR 1200E	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	20	30	40	50	60	80	100	150	200	V
Maximum RMS Voltage	V <sub>RMS</sub>	14	21	28	35	42	56	70	105	140	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	20	30	40	50	60	80	100	150	200	V
Maximum Average Forward Rectified Current at T <sub>C</sub> = 75°C	I <sub>F(AV)</sub>	1.0									A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	22									A
Typical Thermal Resistance <sup>NOTE1</sup>	R <sub>θJA</sub> R <sub>θJL</sub>	220 50									°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 ~ +150									°C
Storage Temperature Range	T <sub>STG</sub>	-65 ~ +150									°C

## ELECTRICAL CHARACTERISTICS RATINGS

at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	MBR 120E	MBR 130E	MBR 140E	MBR 150E	MBR 160E	MBR 180E	MBR 1100E	MBR 1150E	MBR 1200E	Unit
Maximum Instantaneous Forward Voltage at (I <sub>F</sub> =0.7 A, T <sub>J</sub> =25°C) (I <sub>F</sub> =1.0 A, T <sub>J</sub> =25°C)	V <sub>F</sub>		0.48 0.55			0.70	0.85	0.90	0.92		V
Maximum DC Reverse Current at Rated DC Blocking Voltage T <sub>A</sub> =25°C T <sub>J</sub> =125°C	I <sub>R</sub>	0.02 10									mA
Typical junction capacitance at 4.0V, 1MHz	C <sub>J</sub>	160									pF

NOTE1: 8.0mm<sup>2</sup> (.013mm thick) land areas



## TYPICAL CHARACTERISTICS

Figure 1. Forward Current Derating Curve

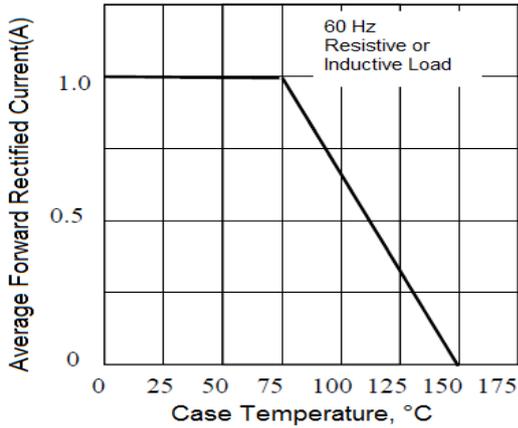


Figure 3. Typical Instantaneous Forward Characteristics

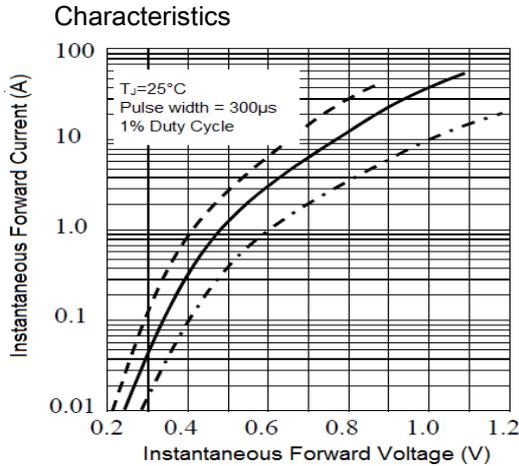


Figure 5. Typical Transient Thermal Impedance

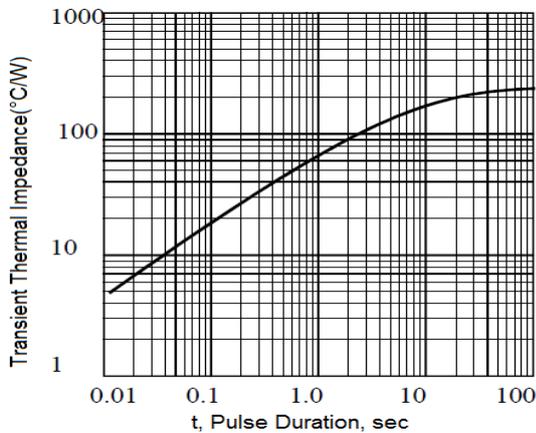


Figure 2. Maximum Non-repetitive Peak Forward Surge Current

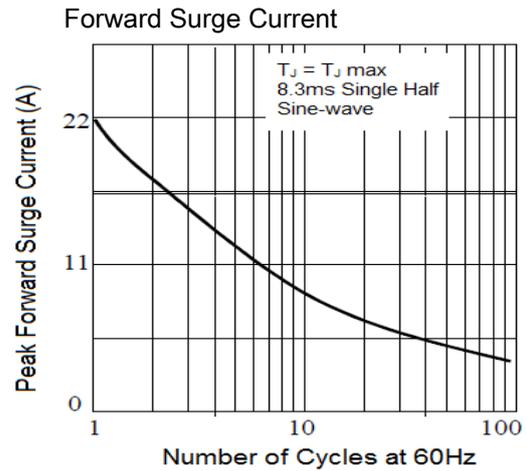


Figure 4. Typical Reverse Characteristics

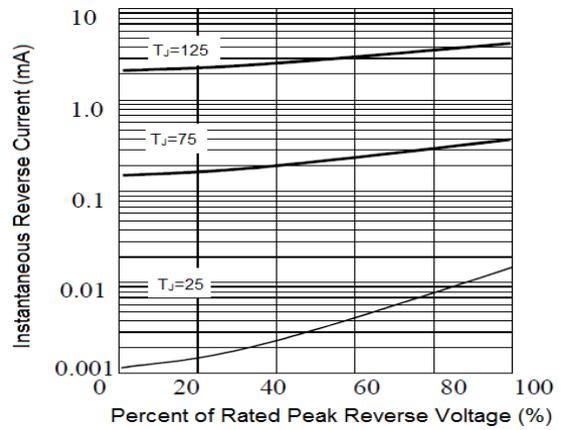
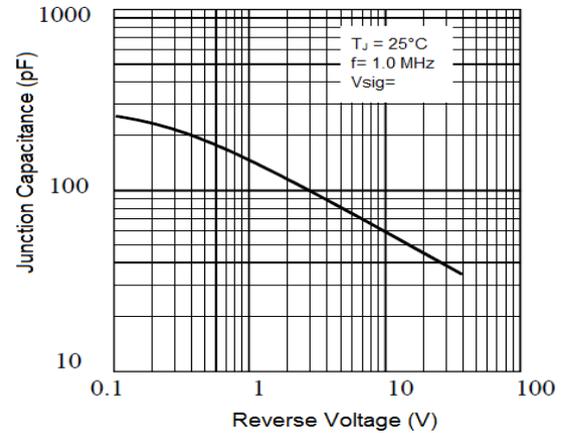


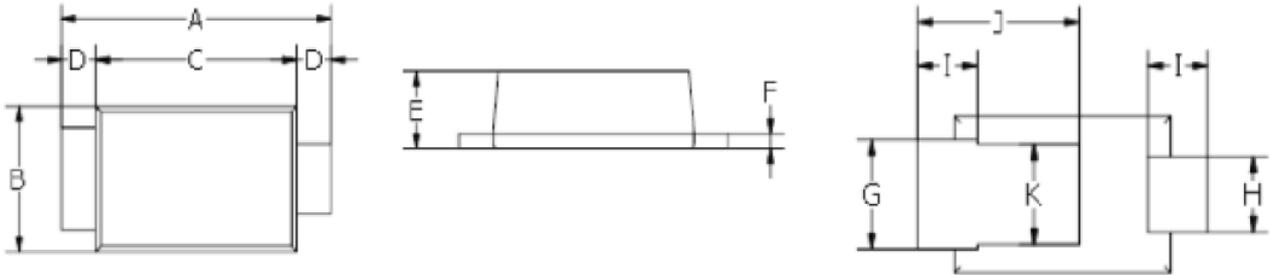
Figure 6. Typical Junction Capacitance





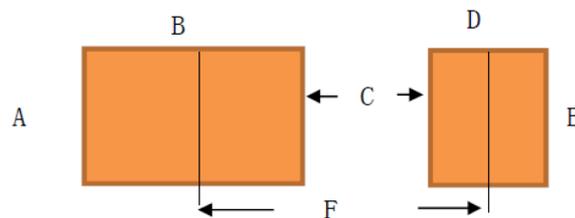
**PACKAGE INFORMATION**

Dimension in SOD-323HE (Unit: mm)



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	2.300	2.700	0.091	0.106
B	1.200	1.400	0.047	0.055
C	1.750	1.950	0.069	0.077
D	0.300 TYP		0.012 TYP	
E	0.550	0.750	0.022	0.030
F	0.100	0.200	0.004	0.008
G	0.650	0.950	0.026	0.037
H	0.500	0.700	0.020	0.028
I	0.400	0.800	0.016	0.031
J	1.150	1.550	0.045	0.061
K	0.800 TYP		0.032 TYP	

Suggested solder pad layout



Dimensions in inches and (millimeters)

Package	A	B	C	D	E	F
SOD-323HE	0.044(1.10)	0.079(2.00)	0.019(0.5)	0.032(0.8)	0.040(1.00)	0.075(1.90)



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